

# Designer's™ Data Sheet

## SWITCHMODE™ Power Rectifier

### D2PAK Surface Mount Power Package

**MBRB2060CT**

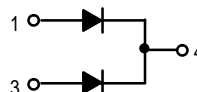
Motorola Preferred Device

Employs the use of the Schottky Barrier principle with a platinum barrier metal. These state-of-the-art devices have the following features:

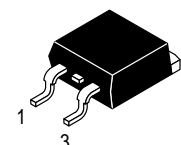
- Package Designed for Power Surface Mount Applications
- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL94, V<sub>O</sub> at 1/8"
- Guaranteed Reverse Avalanche
- Short Heat Sink Tab Manufactured — Not Sheared!
- Similar in Size to Industry Standard TO-220 Package

#### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 units per plastic tube
- Available in 24 mm Tape and Reel, 800 units per 13" reel by adding a "T4" suffix to the part number
- Marking: B2060T



**SCHOTTKY BARRIER  
RECTIFIER  
20 AMPERES  
60 VOLTS**



**CASE 418B-02**

#### MAXIMUM RATINGS, PER LEG

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	60	Volts
Average Rectified Forward Current (Rated V <sub>R</sub> ) T <sub>C</sub> = 110°C	I <sub>F(AV)</sub>	10 20	Amps
Total Device			
Peak Repetitive Forward Current (Rated V <sub>R</sub> , Square Wave, 20 kHz), T <sub>C</sub> = 100°C	I <sub>FRM</sub>	20	Amps
Non-repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	150	Amps
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I <sub>RRM</sub>	0.5	Amp
Storage Temperature	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	T <sub>J</sub>	-65 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10000	V/μs

#### THERMAL CHARACTERISTICS, PER LEG

Thermal Resistance — Junction to Case — Junction to Ambient (1)	R <sub>θJC</sub> R <sub>θJA</sub>	2.0 50	°C/W
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(1) See Chapter 7 for mounting conditions

**Designer's Data for "Worst Case" Conditions** — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

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**Preferred** devices are Motorola recommended choices for future use and best overall value.

# MBRB2060CT

## ELECTRICAL CHARACTERISTICS, PER LEG

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (2) ( $i_F = 20$ Amps, $T_J = 125^\circ\text{C}$ ) ( $i_F = 20$ Amps, $T_J = 25^\circ\text{C}$ )	$v_F$	0.85 0.95	Volts
Maximum Instantaneous Reverse Current (2) (Rated dc Voltage, $T_J = 125^\circ\text{C}$ ) (Rated dc Voltage, $T_J = 25^\circ\text{C}$ )	$i_R$	150 0.15	mA

(2) Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

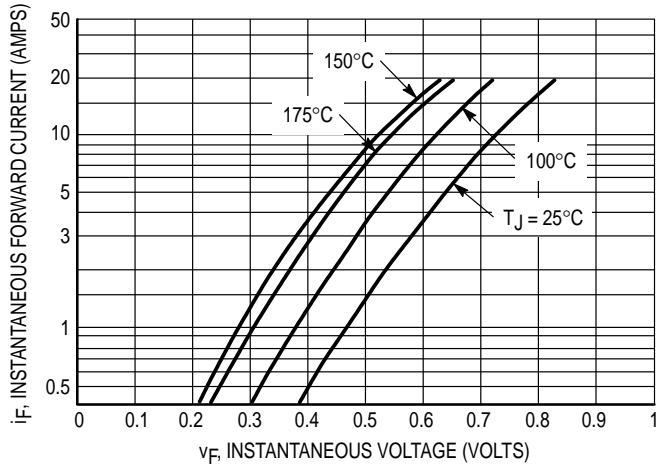


Figure 1. Typical Forward Voltage Per Diode

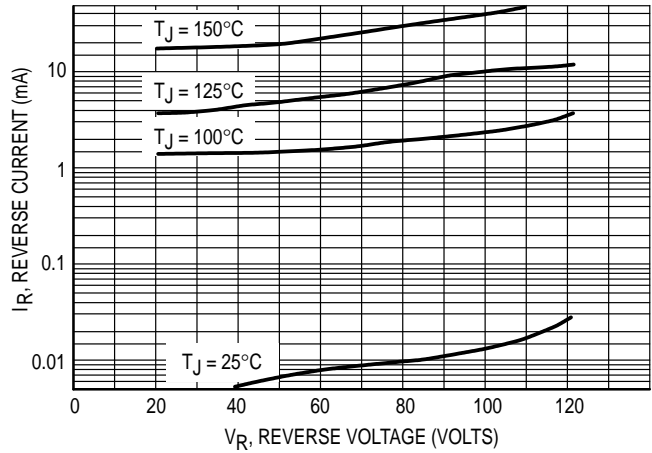


Figure 2. Typical Reverse Current Per Diode

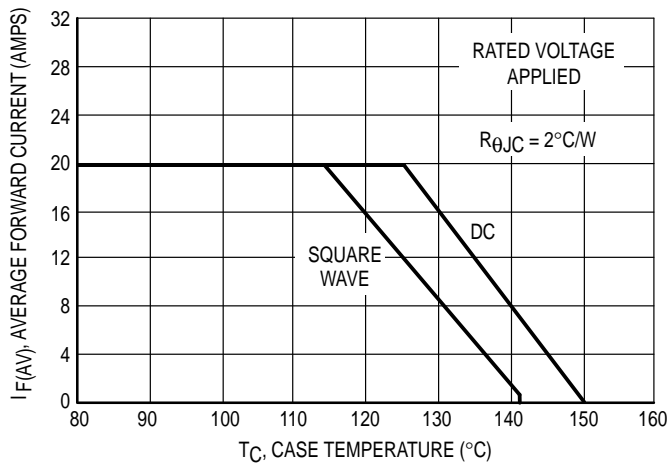


Figure 3. Typical Current Derating, Case, Per Leg

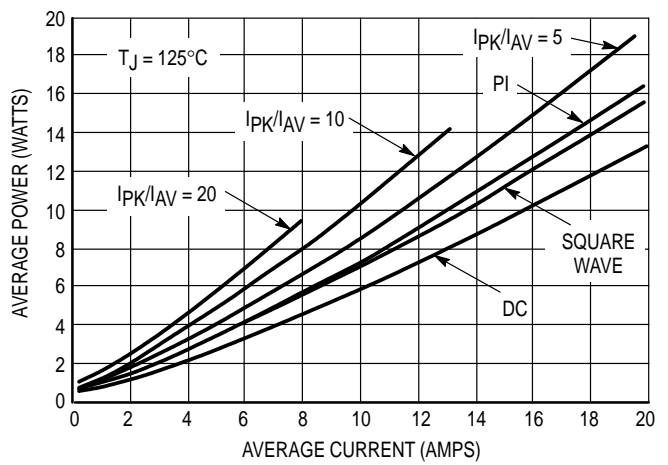


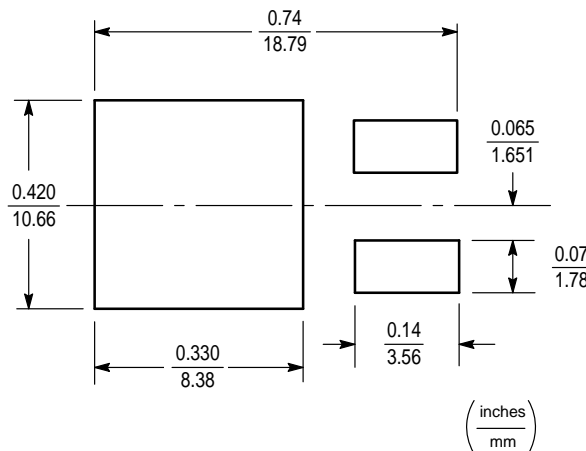
Figure 4. Average Power Dissipation and Average Current

## INFORMATION FOR USING THE D<sup>2</sup>PAK SURFACE MOUNT PACKAGE

### MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface

between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



### D<sup>2</sup>PAK POWER DISSIPATION

The power dissipation of the D<sup>2</sup>PAK is a function of the drain pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by  $T_{J(max)}$ , the maximum rated junction temperature of the die,  $R_{\theta JA}$ , the thermal resistance from the device junction to ambient; and the operating temperature,  $T_A$ . Using the values provided on the data sheet for the D<sup>2</sup>PAK package,  $P_D$  can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature  $T_A$  of 25°C, one can calculate the power dissipation of the device which in this case is 2.5 watts.

$$P_D = \frac{150^\circ\text{C} - 25^\circ\text{C}}{50^\circ\text{C/W}} = 2.5 \text{ watts}$$

The 50°C/W for the D<sup>2</sup>PAK package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 2.5 watts. There are other alternatives to achieving higher power dissipation from the D<sup>2</sup>PAK package. One is to increase the area of the drain pad. By increasing the area of the drain pad, the power dissipation can be increased. Although one can almost double the power dissipation with this method, one will be giving up area on the printed circuit board which can defeat the purpose of using surface mount technology.

Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

**SOLDERING PRECAUTIONS**

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.\*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 5 seconds.

- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.

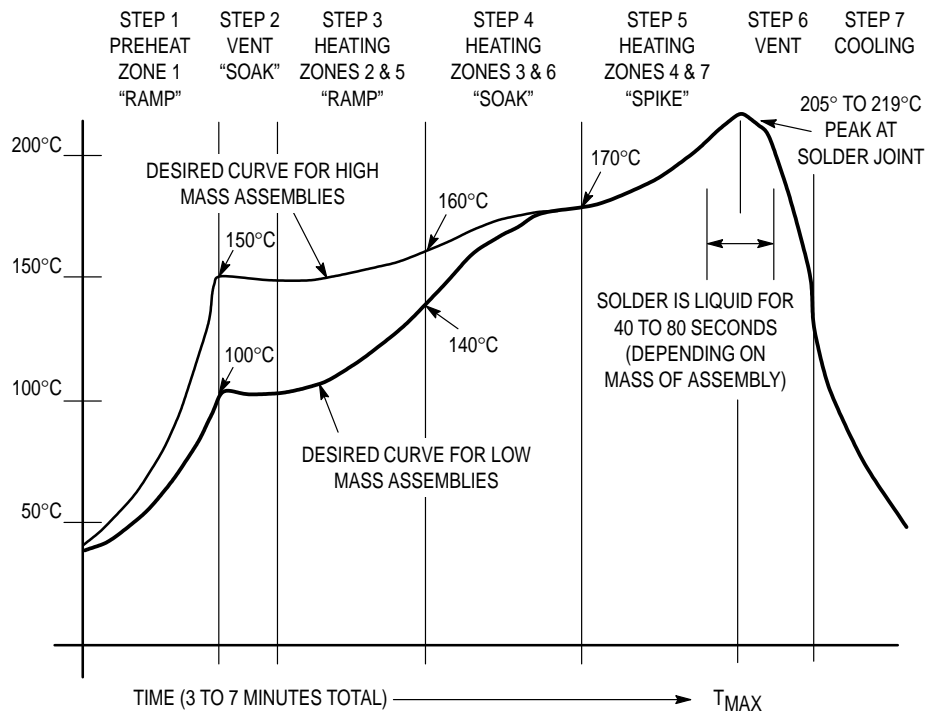
\* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

\* Due to shadowing and the inability to set the wave height to incorporate other surface mount components, the D<sup>2</sup>PAK is not recommended for wave soldering.

**TYPICAL SOLDERING HEATING PROFILE**

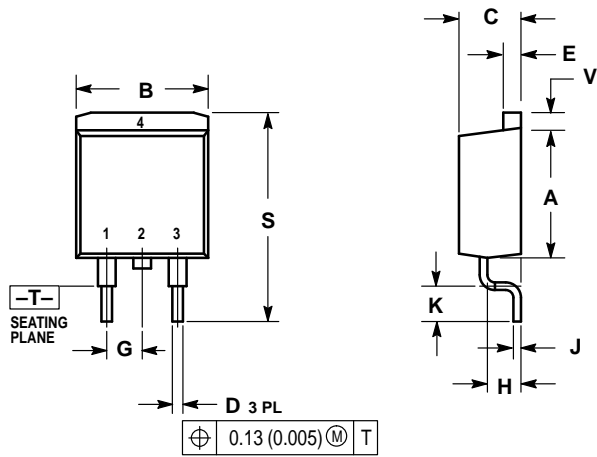
For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating "profile" for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 5 shows a typical heating profile for use when soldering the D<sup>2</sup>PAK to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time. The line on

the graph shows the actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177–189°C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.



**Figure 5. Typical Solder Heating Profile for D<sup>2</sup>PAK**

PACKAGE DIMENSIONS




- NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

- STYLE 3:  
 PIN 1. ANODE  
 2. CATHODE  
 3. ANODE  
 4. CATHODE

CASE 418B-02  
 ISSUE B

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**How to reach us:**

**USA/EUROPE/Locations Not Listed:** Motorola Literature Distribution;  
P.O. Box 5405, Denver, Colorado 80217. 303-675-2140 or 1-800-441-2447

**JAPAN:** Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center,  
3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 81-3-3521-8315

**Mfax™:** RMFAX0@email.sps.mot.com – TOUCHTONE 602-244-6609  
**INTERNET:** <http://Design-NET.com>

**ASIA/PACIFIC:** Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park,  
51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298

